

S-Band, GaN/SiC, 50-Ohm RF Power Transistor

3.1 - 3.5GHz | 135 W typ | 55% Efficiency typ | 13.5dB Gain typ | 46 V | 300µs Pulse Length, 10% Duty Cycle

IGT3135M135 and IGT3135M135S are high power GaN-on-SiC RF power transistors that are fully matched to 50Ω at both the input and output. They supply a minimum of 135W of peak output power, with typically >13.5dB of gain and 62% efficiency. They operate from a 46V supply voltage. For optimal thermal efficiency, the transistors are housed in a metal-based package with an epoxy-sealed ceramic lid.



FEATURES

- GaN on SiC HEMT Technology
- Output Power >135W
- Fully matched to 50Ω at both input and output
- High Efficiency - 55% typical
- 100% RF Tested Under 300µs, 10% duty cycle pulse conditions
- RoHS and REACH Compliant
- IGT3135M135 has a bolt-down flange, IGT3135M135S is the earless flange option

APPLICATIONS

- S-band Radar Systems

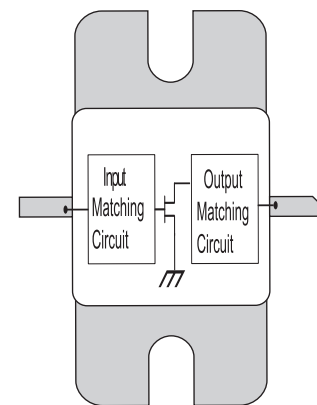


Table 1. Absolute Maximum Ratings (Not Simultaneous)

| Parameter | Symbol | Value | Units | Test Conditions |
|--------------------------------|--------------|-------------|-------|-----------------|
| DC Drain-Source Voltage | V_{DS} | 160 | V | 25 °C |
| DC Gate-Source Voltage | V_{GS} | -8 to +1 | V | 25 °C |
| DC Drain Current | I_D | 12 | A | 25 °C |
| DC Gate Current | I_G | 12 | mA | 25 °C |
| RF Input Power | $P_{RF,IN}$ | 10.7 | W | 25 °C |
| Operating Junction Temperature | T_J | -55 to +200 | °C | |
| Storage Temperature | T_{STG} | -55 to +150 | °C | |
| Soldering Temperature | T_{SOLDER} | 260 for 10s | °C | |

Note: Operation outside the limits given in this table may cause permanent damage to the transistor

Table 2. DC Electrical Characteristics (Case temperature = 25 °C unless otherwise stated)

| Parameter | Symbol | Min | Typ | Max | Units | Test Conditions |
|------------------------|--------|------|------|------|-------|-------------------------------|
| Gate Pinch-Off Voltage | V_P | -4.0 | -3.0 | -2.5 | V | $V_{DS} = 46V, I_{DS} = 2mA$ |
| Quiescent Gate Voltage | V_Q | | -2.6 | | V | $V_{DS} = 46V, I_{DS} = 25mA$ |

Table 3. RF Electrical Characteristics (Case temperature = 30 °C unless otherwise stated)

| Parameter | Symbol | Min | Typ | Max | Units | Test Conditions |
|-------------------------|----------|------|------|------|-------|--|
| Gain | G | 11.0 | 13.5 | 15.5 | dB | $P_{OUT} = 135W$ $f = 3.1, 3.3, 3.5 \text{ GHz}$ 300 μ s pulse length, 10% duty cycle $V_{DS} = 46V, I_{DS} = 25mA$ |
| Drain Efficiency | η | 45 | 55 | 75 | % | |
| Pulse Droop | D | -0.8 | -0.4 | +0.2 | dB | |
| Input Return Loss | IRL | -18 | -10 | -6 | dB | |
| Load Mismatch Stability | VSWR-S | 2:1 | | | | |
| VSWR Withstand | VSWR-LMT | 3:1 | | | | |

Note: Consult Integra Technologies Application Note 001 for information on how RF output power and pulse droop are measured.

Table 4. Thermal Resistance (Case temperature = 25 °C unless otherwise stated)

| Parameter | Symbol | Min | Typ | Max | Units | Test Conditions |
|--|--------------|-----|-----|------|-------|--|
| Peak Thermal Resistance, Channel to Case | $R_{TH(JC)}$ | | | 1.24 | °C/W | $P_{OUT} = 135W$ 55% Efficiency $f = 3.1, 3.3, 3.5 \text{ GHz}$ 300 μ s pulse length, 10% duty cycle $V_{DS} = 46V, I_{DS} = 25mA$ |

TYPICAL PERFORMANCE

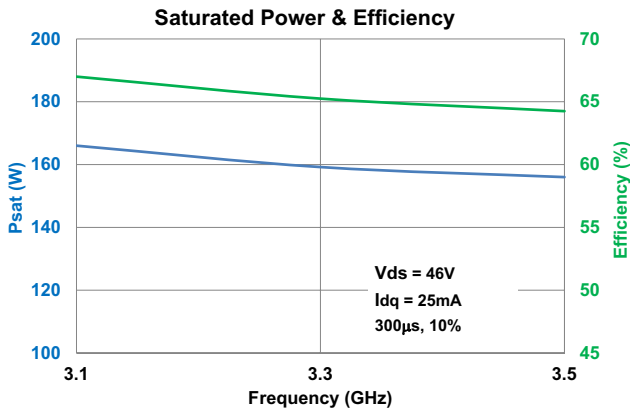


Figure 1

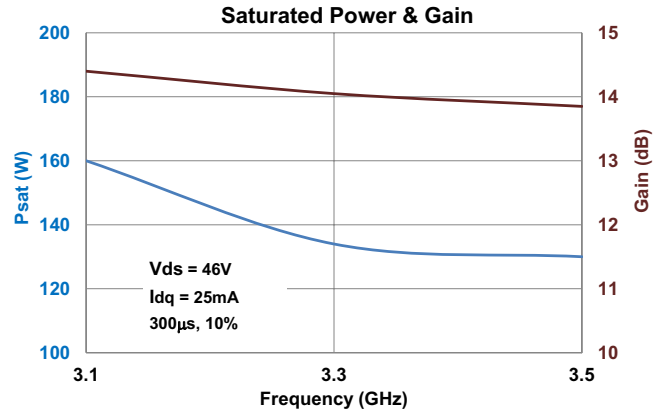


Figure 2

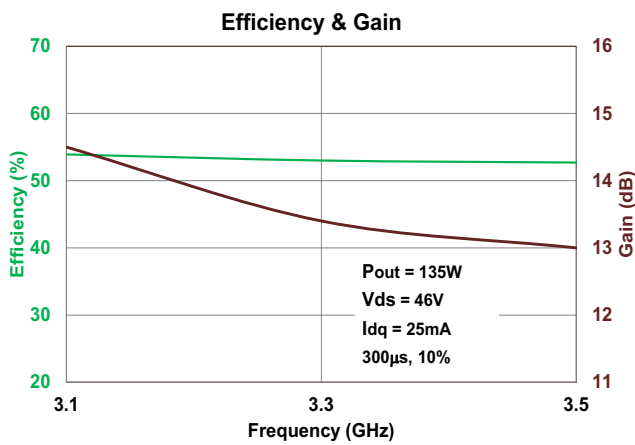


Figure 3

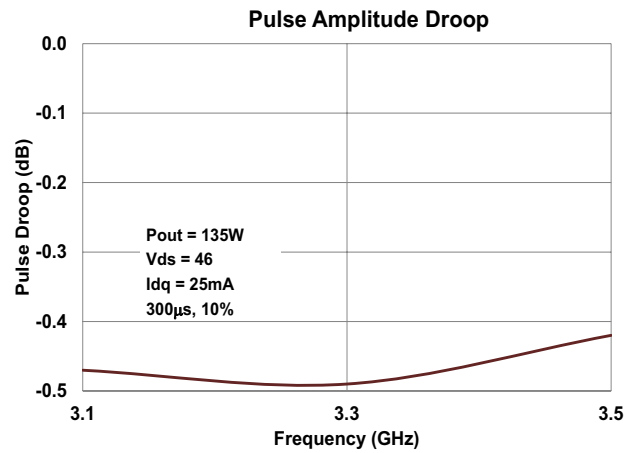


Figure 4

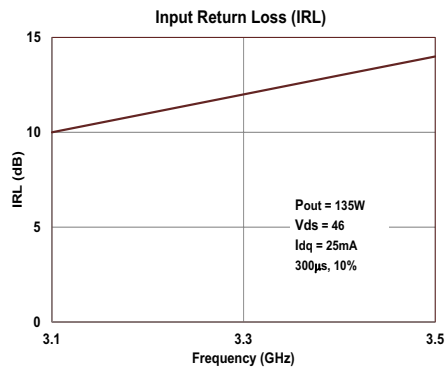
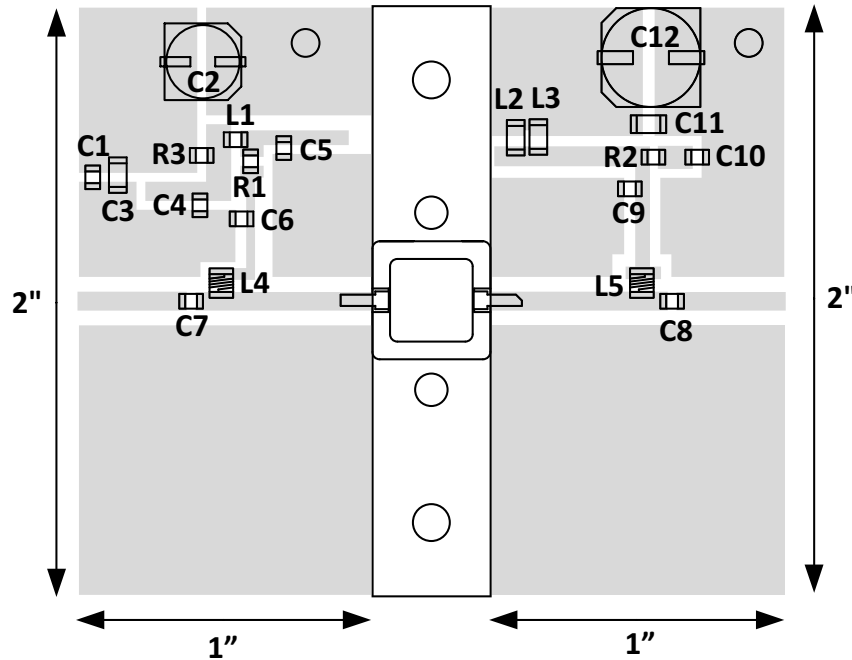


Figure 5

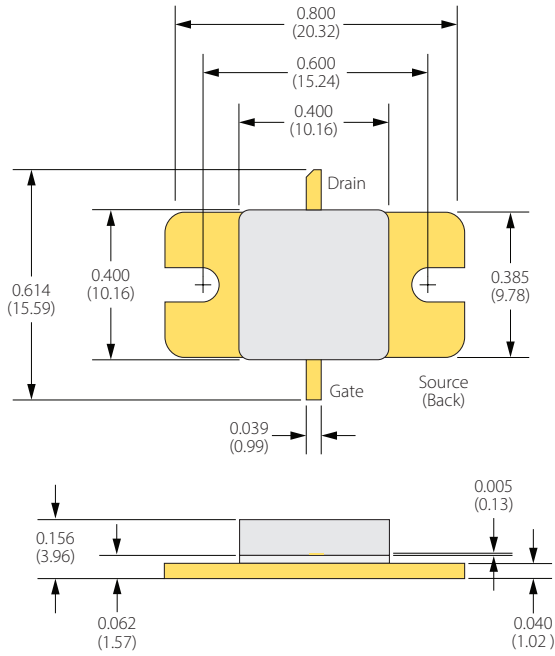
TEST FIXTURE



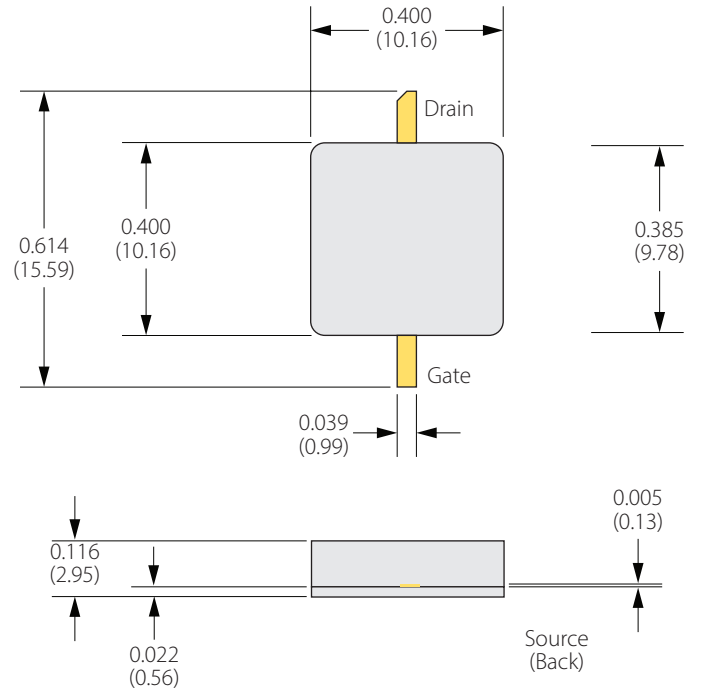
Bill of Materials for IGT3135M135 Test Fixture

| Designator | Description | Quantity | Part Number |
|-------------|--|----------|--------------------|
| C1, C4, C10 | CAP 0.1µF, 0805, 100V | 3 | C0805C104K1RAL |
| C2 | CAP 47µF, 20%, SMD, Polymer | 1 | PCV1E470MCL2GS |
| C3, C11 | CAP 1µF, 1206, 100V, X7R | 2 | GRM31CR72A105KA01L |
| C5 | CAP, 39pF, 0805 250V | 1 | ATC600F390 |
| C6, C9 | CAP 5.6pF, +/-0.25, 0805, 250V, Edge Mount | 2 | ATC600F5R6CT |
| C7, C8 | CAP 12pF, +/-5%, 0805, 250V | 2 | ATC600F120CT |
| C12 | CAP 68µF, 20%, 63V, SMD | 1 | EEE-FK1J680P |
| L1 | IND FB 120Ω, 0805, 5A | 1 | ILHB0805ER121V |
| L2, L3 | IND FB 33Ω@100MHz, 1206, 6A | 2 | BLM31PG330S |
| L4, L5 | IND 22nH, 0908 | 2 | 0908SQ-22NGL |
| R1, R2 | RES 100Ω, 0805 | 2 | |
| R3 | RES 470Ω, 0805 | 1 | |
| PC Board | DK=3.6, 30 mils, 1oz/1oz Copper | 2 | RO4350B-03011 |

PACKAGE PL44A1



**BOLT-DOWN FLANGE OPTION
 IGT3135M135**



**EARLESS FLANGE OPTION
 IGT3135M135S**

Dimensions: Inches (mm)

ESD & MSL Rating

| Parameter | Rating | Standard |
|----------------------------------|----------------------|------------------------|
| ESD Human Body Model (HBM) | TBD | ESDA/JEDEC JS-001-2012 |
| ESD Charged Device Model (CDM) | TBD | JEDEC JESD22-C101F |
| Moisture Sensitivity Level (MSL) | Unlimited Shelf Life | IPC/JEDEC J-STD-020 |

RoHS Compliance

Integra Technologies, Inc declares that its GaN and LDMOS Transistor Products comply with EU Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863/EU.

REACH Compliance

Integra Technologies supports EU Regulation number 1907/2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) as these apply to Integra semiconductor products, development tools, and shipping packaging.

In support of the REACH regulation, Integra will:

- Inform customers and recipients of Integra product if they contain any substances that are of very high concern (SVHC) per the European Chemical Agency (ECHA) website.
- Notify ECHA if any Integra product that contains any SVHCs which exceed guidelines for REACH chemicals by weight per part number and for total content weight per year for all products produced in or imported to the European market.
- Cease shipments of product containing REACH Annex XIV substances until authorization has been obtained.
- Cease shipment of product containing REACH Annex XVII chemicals when restrictions apply.

Integra has evaluated its materials, BOMs, and product specifications and product and has determined that this transistor conforms to all REACH and SVHC regulations and guidelines. Integra has implemented actions and control programs that will assure continued compliance.

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DEFINITIONS:

DATA SHEET STATUS

Advanced Specification - This data sheet contains Advanced specifications.

Preliminary Specification - This data sheet contains specifications based on preliminary measurements and data.

Final Specification - This data sheet contains final product specifications.

MAXIMUM RATINGS Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.